

CMOS Digital Integrated Circuit Silicon Monolithic

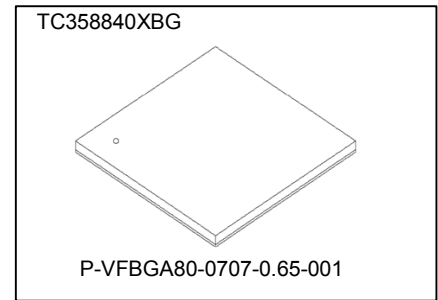
TC358840XBG

Mobile Peripheral Devices

Overview

TC358840XBG, Ultra HD to CSI-2, bridge converts high resolution (higher than 4 Gbps) HDMI® stream to MIPI® CSI-2 Tx video. It is a follow up device of TC358743XBG. The HDMI-RX runs at 297 MHz to carry up to 7.2 Gbps video stream. It requires dual link MIPI CSI-2 Tx, 1 Gbps/data lane, to transmit out a maximum 7.2 Gbps video data.

The bridge chip is necessary for current and next generation Application Processors which have been designed without video stream input port except CSI-2 Rx.



Weight: 67 mg (Typ.)

Features

● HDMI-RX Interface

- ◇ HDMI 1.4b
 - Video Formats Support (Up to 4K×2K / 30fps), maximum 24 bps (bit-per-pixel) no deep color support
 - RGB, YCbCr444: 24-bpp
 - YCbCr422: 24-bpp
 - Color Conversion
 - 4:2:2 to 4:4:4 is supported
 - 4:4:4: to 4:2:2 is supported
 - RGB888 to YCbCr (4:4:4 / 4:2:2) is supported
 - YCbCr (4:4:4 / 4:2:2) to RGB888/666 is supported
 - ◇ Note: for RGB666 (R=R[5:0],2'b00, G=G[5:0],2'b00, B=B[5:0],2'b00)
 - Maximum HDMI clock speed: 297 MHz
 - Audio Supports
 - Internal Audio PLL to track N/CTS value transmitted by the ACR packet.
 - 3D Support
 - Support HDCP1.4 decryptions
 - EDID Support, Release A, Revision 1 (Feb 9, 2000)
 - First 128 byte (EDID 1.3 structure)
 - First E-EDID Extension: 128 bytes of CEA Extension version 3 (specified in CEA-861-D)
 - Embedded 1K-byte SRAM (EDID_SRAM)
- ◇ Does not support Audio Return Path and HDMI Ethernet Channels

● CSI-2 TX Interface (This function is supported only by TC358840XBG)

- ◇ MIPI CSI-2 compliant (Version 1.01 Revision 0.04 – 2 April 2009)
- ◇ Dual links CSI-2 (CSI0 and CSI1), each link supports 4 data lanes @ 1 Gbps/data lane
 - CSI0 carries the left half data of HDMI Rx video stream and CSI1 carries the right one at the default configuration.
 - Left or right data can be assigned/programmed to

either CSI-2 Tx link

- The maximum length of each half is limited to 2048-pixel, CSI0 data length could be different from that of CSI1's
- The maximum Hsync skew between CSI0 and CSI1 can be less than 10 ByteClk
- ◇ Single link CSI-2, maximum horizontal pixel width
 - 2558 pixels (24-bit per pixel)
 - 3411 pixels (16-bit per pixel)
- ◇ HDMI InfoFrame data can be transmit over MIPI CSI-2 at the beginning of each frame (after FS short packet)
- ◇ Supports video data formats
 - RGB666, RGB888, YCbCr444, YCbCr 422 24-bit and YCbCr 422 16-bit
 - YCbCr inputs can be converted into RGB before outputting and vice versa.

● I²C Interface

- ◇ Support for normal (100 kHz), fast mode (400 kHz) and ultrafast mode (2 MHz)
- ◇ Slave Mode
 - To be used by an external Master to configure all TC358840XBG internal registers, including EDID_SRAM and panel control
 - Support 2 I²C Slave Addresses (0x0F & 0x1F) selected through boot-strap pin (INT)

● Audio Output Interface

- ◇ Up to four I2S data lines for supporting multi-Channel audio data (5.1 and 7.1)
- ◇ Maximum audio sample frequency supported is 192 kHz @8 CH
- ◇ Support 16, 18, 20 or 24-bit data (depend on HDMI input stream)
- ◇ Support Master Clock output only
- ◇ Support 32 bit-wide time-slot only
- ◇ Output Audio Over Sampling clock (256fs)
- ◇ Either I2S or TDM Audio interface available (pins

are multiplexed)

- ◇ I2S Audio Interface
 - Support Left or Right-justify with MSB first
- ◇ TDM (Time Division Multiplexed) Audio Interface
 - Fixed to 8 channels (depend on HDMI input stream)
- ◇ Digital Audio Interface
 - Supports HBR audio stream split across 4 I2S lines if bandwidth higher than 12 MHz

- **InfraRed (IR)**

- ◇ Support NEC InfraRed protocol.

- **Power supply inputs**

- ◇ Core: 1.15V
- ◇ MIPI D-PHY: 1.2V
- ◇ I/O: 1.8V, 3.3V
- ◇ HDMI: 3.3V
- ◇ APLL: 3.3V

- **Power Consumption during typical operations**

- ◇ 1920×1080 @60 fps: 420 mW (Dual D-PHY link)
- ◇ 2560×1600 @60 fps: 504 mW (Dual D-PHY link)
- ◇ 3840×2160 @30 fps: 520 mW (Dual D-PHY link)

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1. MIPI D-PHY, "MIPI_D-PHY_specification_v01-00-00, May 14, 2009"
2. MIPI CSI-2, "MIPI Alliance Standard for Camera Serial Interface 2 (CSI-2) Version 1.01 Revision Nov 2010"
3. HDMI, "High-Definition Multimedia Interface Specification Version 1.4a March 4, 2010"
4. I²C bus specification, version 2.1, January 2000, Philips Semiconductor

1. Overview

TC358840XBG , Ultra HD to CSI-2, bridge converts high resolution (higher than 4 Gbps) HDMI stream to MIPI CSI-2 Tx video. It is a follow up device of TC358743XBG. The HDMI-RX runs at 297 MHz to carry up to 7.2 Gbps video stream. It requires dual link MIPI CSI-2 Tx, 1 Gbps/data lane, to transmit out a maximum 7.2 Gbps video data.

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TC358840XBG system view block diagrams is shown in Figure 1.1.

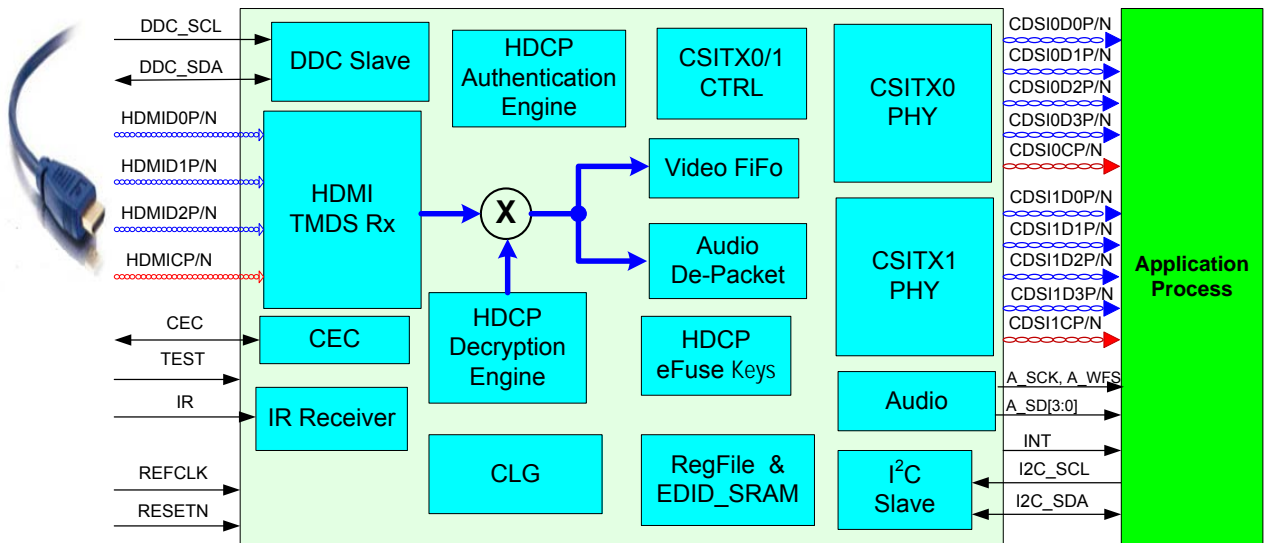


Figure 1.1 TC358840XBG System Overview

2. External Pins

TC358840XBG resides in BGA80 pin packages. The following table gives the signals of TC358840XBG and their function.

Table 2.1 TC358840XBG Functional Signal List

| Group | Pin Name | Ball | I/O | Init (O) | Type (Note) | Function | Voltage Supply |
|---------------------------|----------|------|-----|----------|---------------------------|---|----------------|
| System: Reset & Clock (4) | RESETN | K8 | I | | Sch | System reset input (active low) | VDDIO18 |
| | REFCLK | K9 | I | | Sch | Reference clock input (40 – 50 MHz) | VDDIO18 |
| | TEST | G5 | I | | N | Internal test terminal (Always must be fixed low externally) | VDDIO18 |
| | INT | J3 | O | L | N | Interrupt Output signal (active high) *1 | VDDIO18 |
| CDSI TX0 (10) | CDSI0CP | F10 | O | H | MIPI-PHY | MIPI-CSIO clock positive | VDD12_MIPiO |
| | CDSI0CN | F9 | O | H | MIPI-PHY | MIPI-CSIO clock negative | VDD12_MIPiO |
| | CDSI0D0P | H10 | O | H | MIPI-PHY | MIPI-CSIO data 0 positive | VDD12_MIPiO |
| | CDSI0D0N | H9 | O | H | MIPI-PHY | MIPI-CSIO data 0 negative | VDD12_MIPiO |
| | CDSI0D1P | G10 | O | H | MIPI-PHY | MIPI-CSIO data 1 positive | VDD12_MIPiO |
| | CDSI0D1N | G9 | O | H | MIPI-PHY | MIPI-CSIO data 1 negative | VDD12_MIPiO |
| | CDSI0D2P | E10 | O | H | MIPI-PHY | MIPI-CSIO data 2 positive | VDD12_MIPiO |
| | CDSI0D2N | E9 | O | H | MIPI-PHY | MIPI-CSIO data 2 negative | VDD12_MIPiO |
| | CDSI0D3P | D10 | O | H | MIPI-PHY | MIPI-CSIO data 3 positive | VDD12_MIPiO |
| CDSI0D3N | D9 | O | H | MIPI-PHY | MIPI-CSIO data 3 negative | VDD12_MIPiO | |
| CDSI TX1 (10) | CDSI1CP | A7 | O | H | MIPI-PHY | MIPI-CSI1 clock positive | VDD12_MIPi1 |
| | CDSI1CN | B7 | O | H | MIPI-PHY | MIPI-CSI1 clock negative | VDD12_MIPi1 |
| | CDSI1D0P | A9 | O | H | MIPI-PHY | MIPI-CSI1 data 0 positive | VDD12_MIPi1 |
| | CDSI1D0N | B9 | O | H | MIPI-PHY | MIPI-CSI1 data 0 negative | VDD12_MIPi1 |
| | CDSI1D1P | A8 | O | H | MIPI-PHY | MIPI-CSI1 data 1 positive | VDD12_MIPi1 |
| | CDSI1D1N | B8 | O | H | MIPI-PHY | MIPI-CSI1 data 1 negative | VDD12_MIPi1 |
| | CDSI1D2P | A6 | O | H | MIPI-PHY | MIPI-CSI1 data 2 positive | VDD12_MIPi1 |
| | CDSI1D2N | B6 | O | H | MIPI-PHY | MIPI-CSI1 data 2 negative | VDD12_MIPi1 |
| HDMI-RX (9) | HDMICP | C1 | I | | HDMI-PHY | HDMI clock channel positive | VDD33_HDMI |
| | HDMICN | C2 | I | | HDMI-PHY | HDMI clock channel negative | VDD33_HDMI |
| | HDMID0P | D1 | I | | HDMI-PHY | HDMI data 0 channel positive | VDD33_HDMI |
| | HDMID0N | D2 | I | | HDMI-PHY | HDMI data 0 channel negative | VDD33_HDMI |
| | HDMID1P | E1 | I | | HDMI-PHY | HDMI data 1 channel positive | VDD33_HDMI |
| | HDMID1N | E2 | I | | HDMI-PHY | HDMI data 1 channel negative | VDD33_HDMI |
| | HDMID2P | F1 | I | | HDMI-PHY | HDMI data 2 channel positive | VDD33_HDMI |
| | HDMID2N | F2 | I | | HDMI-PHY | HDMI data 2 channel negative | VDD33_HDMI |
| | REXT | A1 | I | | HDMI-PHY | External reference resistor (Connect with 2kΩ to VDD33HDMI) | VDD33_HDMI |
| DDC (2) | DDC_SCL | A3 | IO | | Sch/5V/OD | DDC I ² C slave clock | VDDIO33 |
| | DDC_SDA | B3 | IO | | Sch/5V/OD | DDC I ² C slave data | VDDIO33 |
| CEC(1) | CEC | A2 | IO | | Sch/OD | CEC signal | VDDIO33 |
| HPD(2) | HPDI | A4 | I | | 5V | 5V power input | VDDIO33 |
| | HPDO | B4 | O | L | N | Hot plug detect output | VDDIO33 |
| Audio (7) | A_SCK | K7 | O | L | N | I2S/TDM bit clock signal | VDDIO18 |
| | A_WFS | K5 | O | L | N | I2S word clock TDM frame sync signal | VDDIO18 |
| | A_SD3 | J5 | O | L | N | I2S data signal bit3 | VDDIO18 |
| | A_SD2 | J6 | O | L | N | I2S data signal bit2 | VDDIO18 |
| | A_SD1 | J8 | O | L | N | I2S data signal bit1 | VDDIO18 |
| | A_SD0 | J9 | O | L | N | I2S data signal bit0 TDM data signal | VDDIO18 |
| | A_OSCK | J4 | O | L | N | Audio Over Sampling Clock | VDDIO18 |
| IR(1) | IR | G6 | I | | N | InfraRed signal (Fix low externally, if not used) | VDDIO18 |
| I2C(2) | I2C_SCL | K4 | IO | | Sch/OD | I ² C slave clock | VDDIO18 |
| | I2C_SDA | K3 | IO | | Sch/OD | I ² C slave data | VDDIO18 |

| | | | | | | | |
|------------------|-------------|--|---|---|-------|--|---------|
| Audio PLL (4) | BIASDA | J1 | O | L | PLL | Audio PLL BIAS signal Connect to AVSS through 0.1 μF when not used | VDDIO33 |
| | DAOUT | J2 | O | H | PLL | Audio PLL Clock Reference output clock Please leave open when not used | VDDIO33 |
| | PCKIN | K1 | I | | PLL | Audio PLL Reference Input clock Connect to AVSS through 0.1 μF when not used | VDDIO33 |
| | PFIL | K2 | O | L | PLL | Audio PLL Low Pass Filter signal Connect to AVSS through 0.1 μF when not used | VDDIO33 |
| POWER (10) | VDDC11 | C10 K6 | - | | Power | 1.1V Internal core power supply | - |
| | VDDIO18 | J7 | - | | Power | 1.8V IO power supply | - |
| | VDDIO33 | H2 | - | | Power | 3.3V IO power supply | - |
| | VDD33_HDMI | B1 G1 | - | | Power | HDMI Phy 3.3V power supply | - |
| | VDD11_HDMI | B2 G2 | - | | Power | HDMI Phy 1.1V power supply | - |
| | VDD12_MIPI0 | J10 | - | | Power | MIPI CSI2 1.2V power supply for link0 | - |
| | VDD12_MIPI1 | B10 | - | | Power | MIPI CSI2 1.2V power supply for link1 | - |
| Ground (18) | VSS | A10 C9 D4 D5 D6 D7 E4 E5 E6 E7 F4 F5 F6 F7 G4 G7 H1 K10 | - | | - | Ground | - |

Total 80 pins

Note: Descriptions mean below.

- N: Normal digital I/O
- Sch: Schmitt trigger input
- 5V: 5V tolerant input
- OD: Open drain
- *1: Pull-Up to select 0x1F for I²C Slave address
Pull-Down to select 0x0F for I²C Slave address

Please consult a technical support representative before board design to determine whether pull-up or pull-down with external resistors.

2.1. TC358840XBG 80-Pin Count Summary

Table 2.2 BGA80 Pin Count Summary

| Group Name | Pin Count | Notes |
|------------------------|-----------|-------------------|
| System | 4 | - |
| CDSI TX0 | 10 | - |
| CDSI TX1 | 10 | - |
| HDMI-RX | 9 | - |
| DDC | 2 | - |
| CEC | 1 | - |
| Audio | 7 | - |
| I2C | 2 | - |
| IR | 1 | - |
| HPD | 2 | - |
| Audio PLL | 4 | - |
| POWER | 10 | IO, Core |
| Ground | 18 | IO, Core, Analog |
| TOTAL Pin Count | 80 | Func 52 + (10+18) |

2.2. Pin Layout

P-VFBGA80-0707-0.65-001

Top view

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 |
|---|------------------|------------------|---------------|---------------|----------------|----------------|---------------|----------------|----------------|--------------------|
| A | A1 REXT | A2 CEC | A3 DDC_SCL | A4 HPDI | A5 CDSI1D3P | A6 CDSI1D2P | A7 CDSI1CP | A8 CDSI1D1P | A9 CDSI1D0P | A10 VSS |
| B | B1 VDD33_HDMI | B2 VDD11_HDMI | B3 DDC_SDA | B4 HPDO | B5 CDSI1D3N | B6 CDSI1D2N | B7 CDSI1CN | B8 CDSI1D1N | B9 CDSI1D0N | B10 VDD12_MIPI1 |
| C | C1 HDMICP | C2 HDMICN | C3 No ball | C4 No ball | C5 No ball | C6 No ball | C7 No ball | C8 No ball | C9 VSS | C10 VDDC11 |
| D | D1 HDMID0P | D2 HDMID0N | D3 No ball | D4 VSS | D5 VSS | D6 VSS | D7 VSS | D8 No ball | D9 CDSI0D3N | D10 CDSI0D3P |
| E | E1 HDMID1P | E2 HDMID1N | E3 No ball | E4 VSS | E5 VSS | E6 VSS | E7 VSS | E8 No ball | E9 CDSI0D2N | E10 CDSI0D2P |
| F | F1 HDMID2P | F2 HDMID2N | F3 No ball | F4 VSS | F5 VSS | F6 VSS | F7 VSS | F8 No ball | F9 CDSI0CN | F10 CDSI0CP |
| G | G1 VDD33_HDMI | G2 VDD11_HDMI | G3 No ball | G4 VSS | G5 TEST | G6 IR | G7 VSS | G8 No ball | G9 CDSI0D1N | G10 CDSI0D1P |
| H | H1 VSS | H2 VDDIO33 | H3 No ball | H4 No ball | H5 No ball | H6 No ball | H7 No ball | H8 No ball | H9 CDSI0D0N | H10 CDSI0D0P |
| J | J1 BIASDA | J2 DAOUT | J3 INT | J4 A_OSCK | J5 A_SD3 | J6 A_SD2 | J7 VDDIO18 | J8 A_SD1 | J9 A_SD0 | J10 VDD12_MIPI0 |
| K | K1 PCKIN | K2 PFIL | K3 I2C_SDA | K4 I2C_SCL | K5 A_WFS | K6 VDDC11 | K7 A_SCK | K8 RESETN | K9 REFCLK | K10 VSS |

HDMI RX

APLL

Figure 2.1 TC358840XBG 80-Pin Layout (Top View)

4. Electrical Characteristics

4.1. Absolute Maximum Ratings

VSS= 0V reference

| Item | Symbol | Rating | Unit |
|--------------------------------------|----------------------|--|------|
| Supply voltage (1.8V - Digital IO) | VDDIO18 | -0.3 to +3.9 | V |
| Supply voltage (3.3V - Digital IO) | VDDIO33 | -0.3 to +3.9 | V |
| Supply voltage (1.1V - Digital Core) | VDDC11 | -0.3 to +1.8 | V |
| Supply voltage (1.2V - MIPI CSI PHY) | VDD12_MIPI | -0.3 to +1.8 | V |
| Supply voltage (3.3V - HDMIRX Phy) | VDD33_HDMI | -0.3 to +3.9 | V |
| Supply voltage (1.1V - HDMIRX Phy) | VDD11_HDMI | -0.3 to +1.8 | V |
| Input voltage (CSI IO) | V _{IN_CSI} | -0.3 to VDD12_MIPI+0.3 | V |
| Output voltage (CSI IO) | V _{OUT_CSI} | -0.3 to VDD12_MIPI+0.3 | V |
| Input voltage (Digital IO) | V _{IN_IO} | -0.3 to VDDIO18+0.3 -0.3 to VDDIO33+0.3 | V |
| Output voltage (Digital IO) | V _{OUT_IO} | -0.3 to VDDIO18+0.3 | V |
| Junction temperature | T _j | 125 | °C |
| Storage temperature | T _{stg} | -40 to +125 | °C |

4.2. Operating Condition

VSS= 0V reference

| Item | Symbol | Min | Typ. | Max | Unit |
|--|----------------------------|-------|------|-------|------|
| Supply voltage (1.8V - Digital IO) | VDDIO18 ^{note} | 1.65 | 1.8 | 1.95 | V |
| Supply voltage (3.3V - Digital IO) | VDDIO33 | 3.0 | 3.3 | 3.6 | V |
| Supply voltage (1.1V - Digital Core) | VDDC11 | 1.1 | 1.15 | 1.2 | V |
| Supply voltage (3.3V - HDMIRX PHY) | VDD33_HDMI | 3.135 | 3.3 | 3.465 | V |
| Supply voltage (1.1V - HDMIRX PHY) | VDD11_HDMI | 1.1 | 1.15 | 1.2 | V |
| Supply voltage (1.2V - MIPI CSI PHY) | VDD12_MIPI0 VDD12_MIPI1 | 1.1 | 1.2 | 1.3 | V |
| Operating temperature (ambient temperature with voltage applied) | T _a | -30 | +25 | +70 | °C |

Note: VDDIO18 can be used at 1.8V or 3.3V.

4.3. DC Electrical Specification

Standard IO

| Item | Symbol | Min | Max | Unit |
|--|-------------------|-------------------------------|-------------------------------|------|
| Input voltage, High level input ^{Note1} | V _{IH} | 0.70 VDDIO18 ^{Note2} | VDDIO18 ^{Note2} | V |
| | | 0.61 VDDIO18 ^{Note3} | VDDIO18 ^{Note3} | |
| | | 0.61 VDDIO33 ^{Note4} | VDDIO33 ^{Note4} | |
| Input voltage, Low level input ^{Note1} | V _{IL} | 0 | 0.30 VDDIO18 ^{Note2} | V |
| | | | 0.25 VDDIO18 ^{Note3} | |
| | | | 0.25 VDDIO33 ^{Note4} | |
| Input voltage High level CMOS Schmitt Trigger ^{Note1} | V _{IHS} | 0.70 VDDIO18 ^{Note2} | VDDIO18 ^{Note2} | V |
| | | 0.61 VDDIO18 ^{Note3} | VDDIO18 ^{Note3} | |
| | | 0.61 VDDIO33 ^{Note4} | VDDIO33 ^{Note4} | |
| Input voltage Low level CMOS Schmitt Trigger ^{Note1} | V _{ILS} | 0 | 0.30 VDDIO18 ^{Note2} | V |
| | | | 0.25 VDDIO18 ^{Note3} | |
| | | | 0.25 VDDIO33 ^{Note4} | |
| Output voltage High level ^{Note1} | V _{OH} | VDDIO18-0.45 ^{Note2} | - | V |
| | | VDDIO18-0.6 ^{Note3} | | |
| | | VDDIO33-0.6 ^{Note4} | | |
| Output voltage Low level ^{Note1} | V _{OL} | - | 0.45 ^{Note2} | V |
| | | | 0.4 ^{Note3 Note4} | |
| Input leak current, High level (Condition: VIN = +VDDIO, VDDIO = 3.6V) | I _{ILH1} | -10 | 10 | μA |
| Input leak current, Low level (Condition: VIN = 0V, VDDIO = 3.6V) | I _{ILL1} | -10 | 10 | μA |

Note1: Each power source is operating within recommended operation condition.

Note2: For IOs related to VDDIO18 and operated at 1.8V range.

Note3: For IOs related to VDDIO18 and operated at 3.3V range.

Note4: For IOs related to VDDIO33.

HDMI DDC Slave IO (DDC_SDA, DDC_SCL terminal)

| Item | Symbol | Min | Max | Unit |
|--|-----------------|-----|------|------|
| Input voltage, High level input | V _{IH} | 3.1 | 5.25 | V |
| Input voltage, Low level input | V _{IL} | 0 | 1.7 | V |
| Output voltage Low level(I _{OL} =8mA) | V _{OL} | - | 0.4 | V |
| Input leak current, High level (VIN=VDDIO33) | I _{IH} | -10 | 10 | μA |
| Input leak current, Low level(VIN=VSS) | I _{IL} | -10 | 10 | μA |

HDMI CEC IO (CEC terminal)

| Item | Symbol | Min | Max | Unit |
|--|-----------------|-----|---------|------|
| Input voltage, High level input | V _{IH} | 2 | VDDIO33 | V |
| Input voltage, Low level input | V _{IL} | 0 | 0.8 | V |
| Output voltage Low level(I _{OL} =8mA) | V _{OL} | - | 0.4 | V |
| Input leak current, High level(VIN=VDDIO33) | I _{IH} | -10 | 10 | μA |
| Input leak current, Low level(VIN=VSS) | I _{IL} | -10 | 10 | μA |

I²C IO (I2C_SDA, I2C_SCL terminal)

| Item | Symbol | Min | Max | Unit |
|--|-----------------|------------|------------|------|
| Input voltage, High level input | V _{IH} | 0.7VDDIO18 | VDDIO18 | V |
| Input voltage, Low level input | V _{IL} | 0 | 0.3VDDIO18 | V |
| Output voltage Low level (VDDIO18 used at 1.8V, I _{OL} =3mA) | V _{OL} | - | 0.2VDDIO18 | V |
| Output voltage Low level (VDDIO18 used at 3.3V, I _{OL} =3mA) | | - | 0.4 | V |

5. External Circuit Recommendation

5.1. I²C Slave address definition

INT terminal is multiplexed with configuring function of I²C Slave address. During **RESETN** asserted, **INT** becomes input and detects the polarity. After **RESETN** deasserted it becomes **INT** function (output) automatically. Pull up or pull down this terminal by 10kohm resister externally.

If pulled up, then I²C Slave address becomes 0x1F
 If pulled down then I²C Slave address becomes 0x0F

5.2. HDMI

DDC_SDA and **DDC_SCL** are pulled up to +5V power line and +5V power line is also pulled down for **DDC_SDA** and **DDC_SDL** to be fixed low when +5V power is disabled.

Below figure illustrates example DDC interface connections.

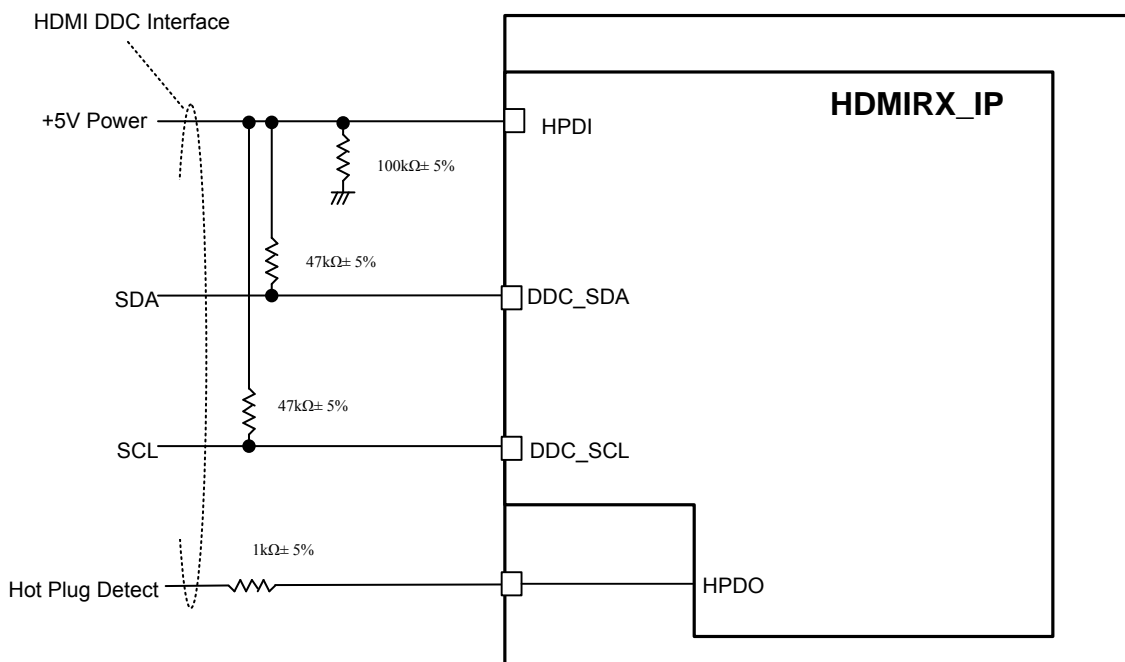


Figure 5.1 Example of DDC I/F Connection

The automatic adjustment function of terminus resistance is attached to HDMI-Rx.
Therefore, connect $2k\Omega \pm 1\%$ of reference resistance between **VDD33_HDMI** and **REXT**.

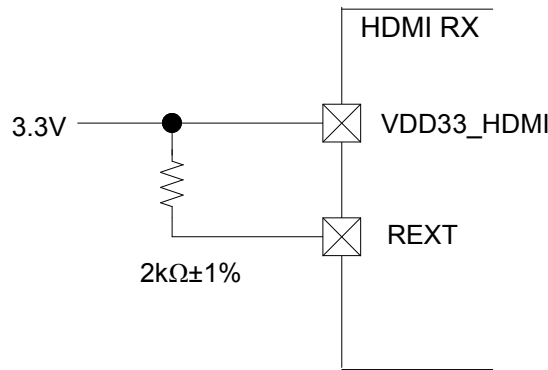


Figure 5.2 Connection of REXT resistance

5.3. Audio PLL

The Audio PLL external terminal connections used in the Audio clock generation are shown in the Figure below.
In **DAOUT** output (PLL input), a low pass filter is installed in the LSI external area.
In addition, a low pass filter for cutting unnecessary components in phase comparator output in the PLL is also installed in the LSI external area.

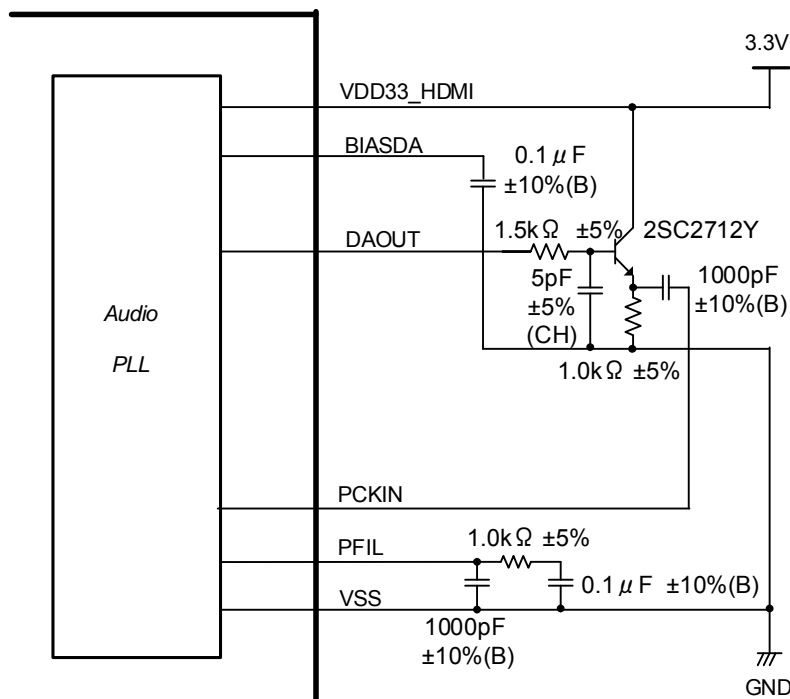


Figure 5.3 Audio Clock External LPF circuit block diagram

5.4. Recommended power supply circuit

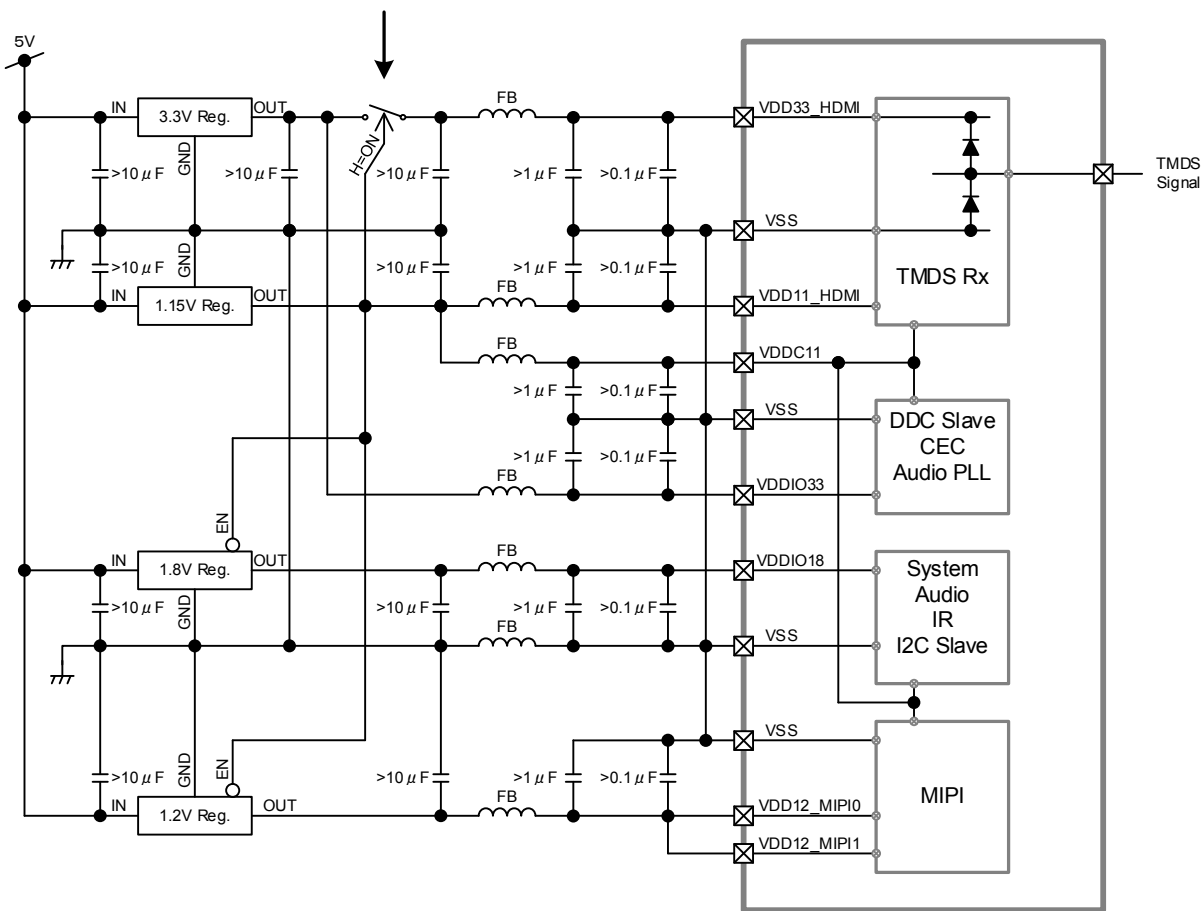
Since the ESD protection diode is attached to the TMDS input pin between a power supply/GND, current may flow backwards HDMI-Rx from source apparatus at the time of power supply OFF.

And also VDD33_HDMI power supply should be isolated from another 3.3V power supplies because this backward current also damages them. Below figure is recommend attaching a back flow prevention circuit.

Case (1) External switch circuit

Attach the adverse current prevention switch from a TMDS differential signal.

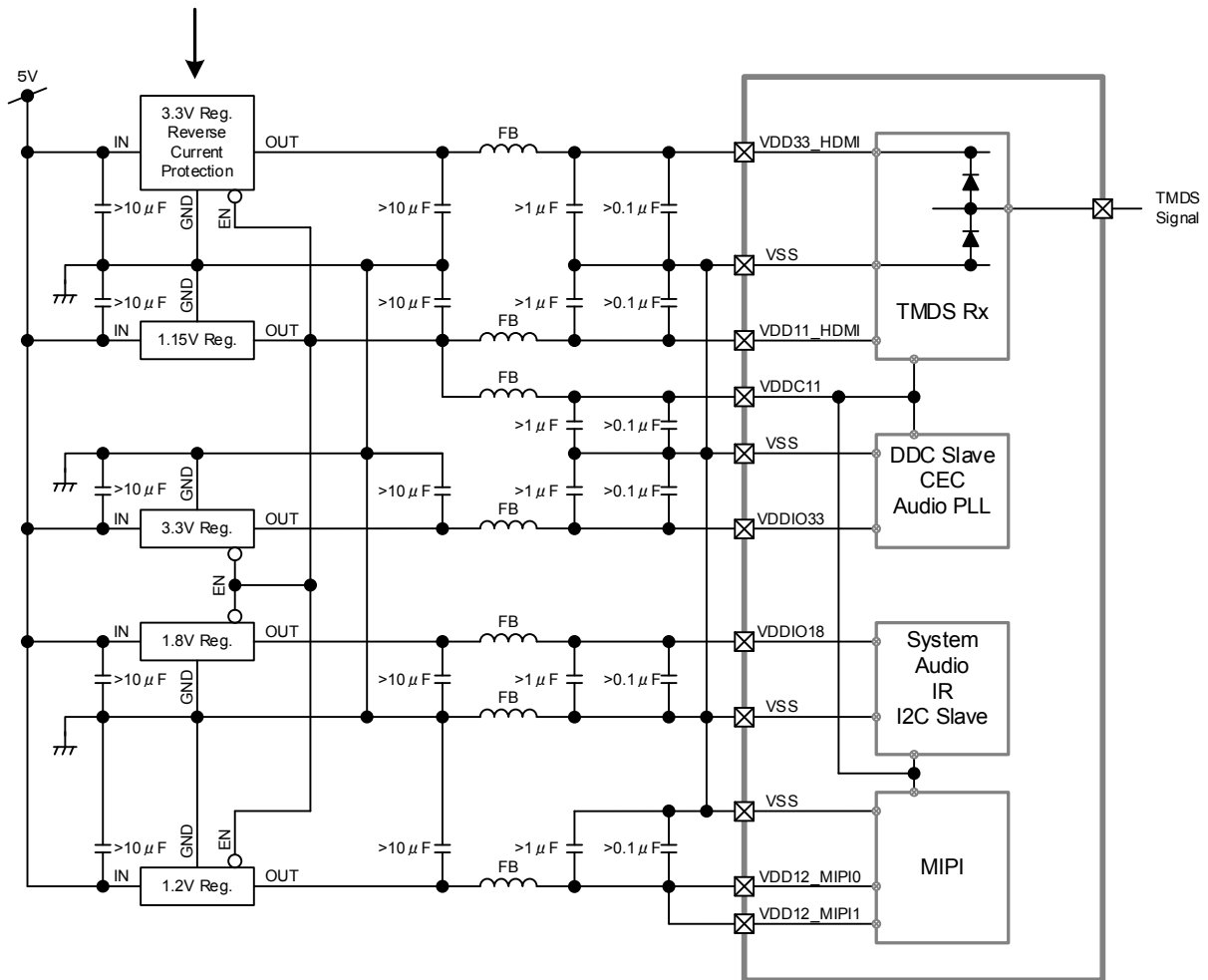
Since reverse current also gives damage to VDDIO33, this switch shall separate VDD33_HDMI and VDDIO33.



All TC358840 VSSs should be separated at AC level from regulators' VSS with FB(ferrite bead) or another method to attenuate EMI.

Figure 5.4 Recommended power supply circuit with external switch

Case (2) Regulator with reverse current protection
 Apply a current protection regulator to VDD33_HDMI.



All TC358840 VSSs should be separated at AC level from regulators' VSS with FB(ferrite bead) or another method to attenuate EMI.

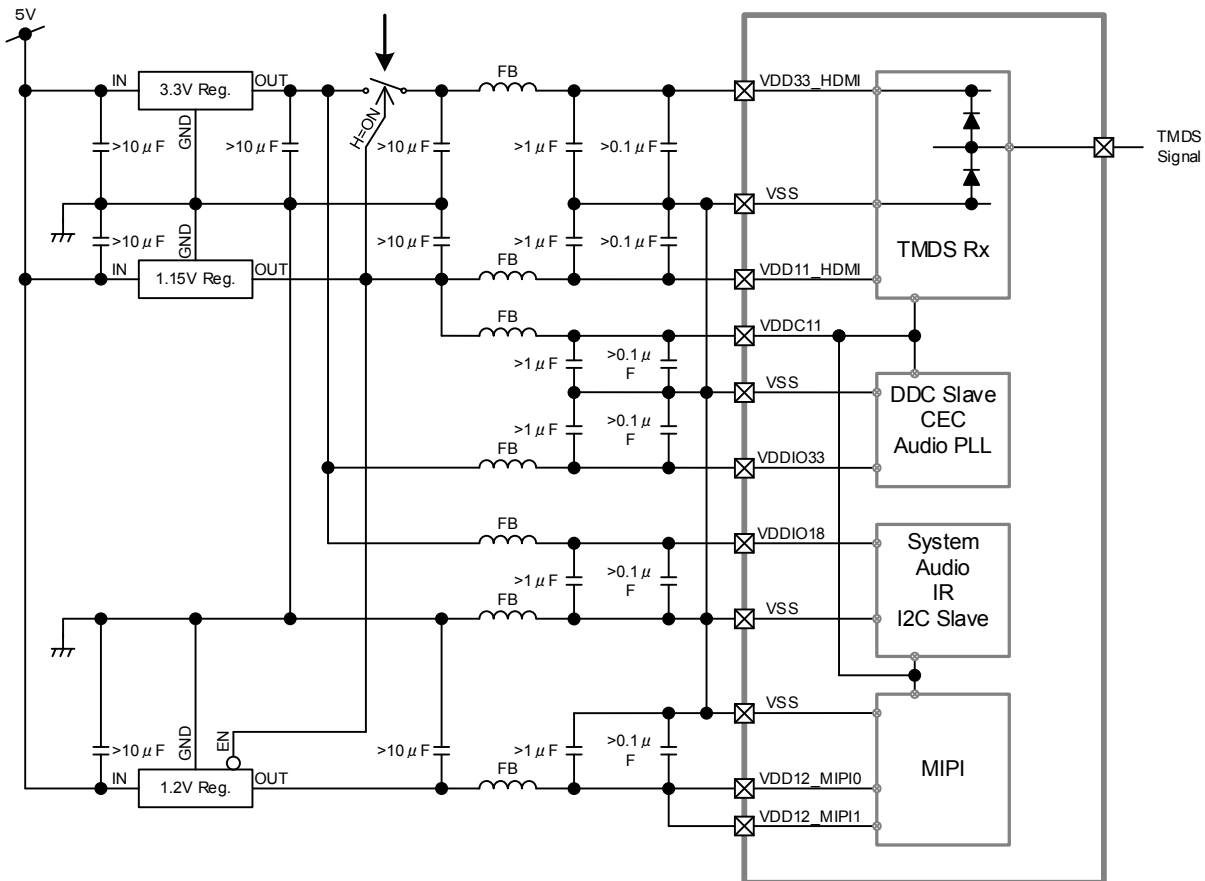
Figure 5.5 Recommended power supply circuit with current protection regulator

Case (3) Use of VDDIO18 at 3.3V range

If VDDIO is applied at 3.3V range, Common regulation is available among VDD33_HDMI, VDIO33 and VDDIO18.

Attach the adverse current prevention switch from a TMDS differential signal.

Since reverse current also gives damage to VDDIO33 and VDDIO18, this switch shall separate VDD33_HDMI and VDDIO33/VDDIO18.



All TC358840 VSSs should be separated at AC level from regulators' VSS with FB(ferrite bead) or another method to attenuate EMI.

Figure 5.6 Recommended power supply circuit at VDDIO18 = 3.3V

6. Revision History

Table 6.1 Revision History

| Revision | Date | Description |
|----------|------------|--|
| 1.0 | 2014-08-01 | New |
| 1.1 | 2014-09-18 | Remove registers 0x5008 and 0x5088 which are redundant Remove Supply Noise Voltage, V_{SN} , from Operation Condition table in section 8.2 Typo fixed 0x04_10 => 0x8410 Add more descriptions for 0x025C, 0x026C, NCO_48F, NCO_44F Correct typo in 0x0150 and 0x01B0 Remove "address 0x85_0F" and adding note |
| 1.51 | 2015-12-18 | Typo Init(O) DAOUT pin in External Pins |
| 1.52 | 2016-04-01 | • Modified the weight of TC358840XBG's package by rounding up digits after the decimal point to form an integer. |

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